

Title (en)  
Crimp terminal

Title (de)  
Crimpklemme

Title (fr)  
Borne de sertissage

Publication  
**EP 2876731 B1 20180502 (EN)**

Application  
**EP 13819977 A 20130719**

Priority  
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Abstract (en)  
[origin: EP2876731A1] In a female crimp terminal 10 having a pressure-bonding section 30 which allows pressure-bonding and connection of at least a conductor tip 201a in an insulated wire 200 obtained by coating a conductor 201 with an insulating cover 202 and having the conductor tip 201a in which the conductor 201 is exposed by peeling off the insulating cover 202 in a tip side, the pressure-bonding section 30 is constructed by arranging a conductor pressure-bonding section 30b and a cover pressure-bonding section 30a from a tip side to a base end side in a long length direction X in this order, the conductor pressure-bonding section 30b pressure-bonding the conductor tip 201a, and the cover pressure-bonding section pressure-bonding a conductor tip portion 202a in the tip side of the insulating cover 202, the cover pressure-bonding section 30a is formed into a hollow shape which can surround the conductor tip portion 202a, and the conductor pressure-bonding section 30b is formed to have a smaller diameter than the cover pressure-bonding section 30a, and is formed into a hollow shape which can surround the conductor tip 201a.

IPC 8 full level  
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